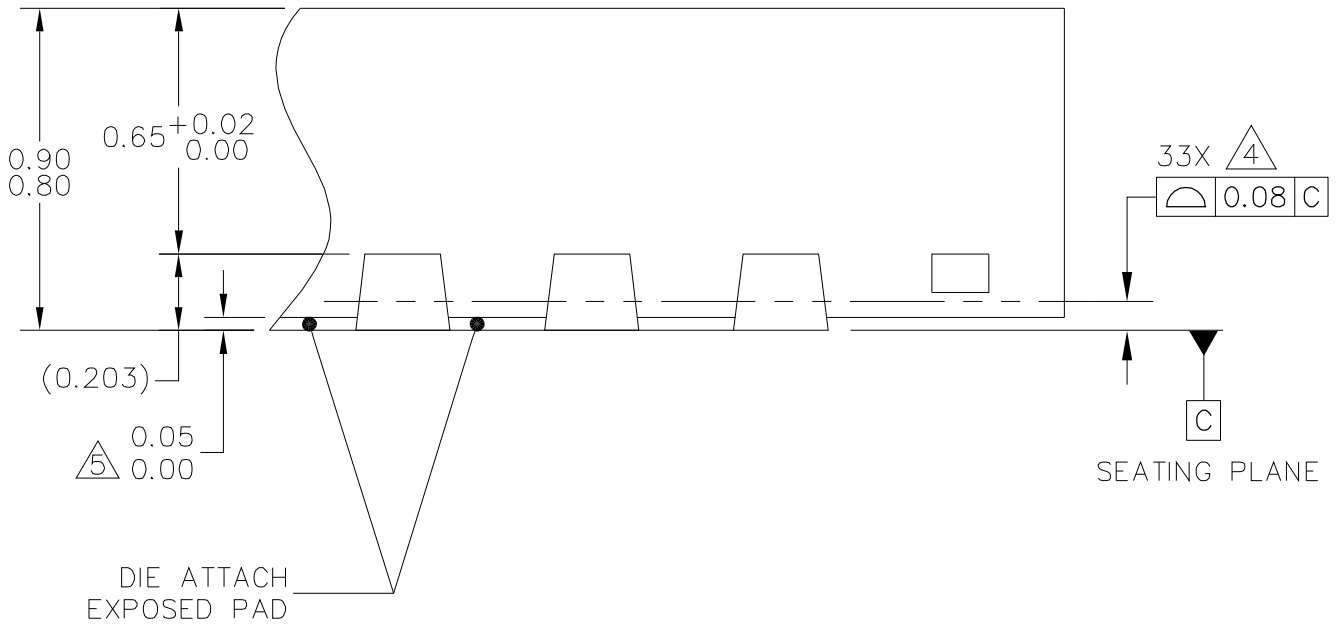


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TITLE: QFN, THERMALLY ENHANCED 5 X 5 X 0.85, 0.5 PITCH, 32 TERMINAL	DOCUMENT NO: 98ASA00625D REV: A	
	STANDARD: NON-JEDEC	
	SOT617-18	11 JAN 2016



DETAIL G
VIEW ROTATED 90° CW

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TITLE: QFN, THERMALLY ENHANCED 5 X 5 X 0.85, 0.5 PITCH, 32 TERMINAL		DOCUMENT NO: 98ASA00625D	REV: A
		STANDARD: NON-JEDEC	
		SOT617-18	11 JAN 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
3. THIS DIMENSION APPLIES TO METALIZED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30MM FROM TERMINAL TIP.
4. BILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. THIS DIMENSION APPLIES ONLY FOR TERMINALS.

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